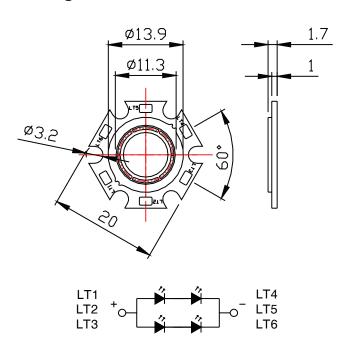




Package Dimensions:



All dimensions are in mm Tolerance: ±0.25mm

Features:

- Pb-Free soldering application
- Multi-Chip package
- · High reliability

Applications:

- Bulb
- · Indoor decoration lighting
- Signal and symbol luminaries
- Reading lights
- Portable flashlight

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation*	Po	1,260	mW
LED Junction Temperature*	Tj	120	V
Reverse Voltage*	Vr	5	mA
D.C. Forward Current*	lr	350	μA
Peak Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)*	If (Peak)	1,000	mA
Storage Temperature Range	Tstg.	-40 to +85	°C
Soldering Temperature (1.6mm from body)	Tsld.	Dip Soldering: 260°C for 10sec. Hand Soldering: 350°C for 3sec.	
Electric Static Discharge Threshold (HBM)*	ESD	300	V

^{*} The values are based on 1 die performance.





Electrical & Optical Characteristics

Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
				300	400		
Luminous Flux	Rank L1	Ф۷	IF=1,050mA	300		400	lm
	Rank L2			400		450	
					6.5		
Forward Voltage	Rank V1	VF	IF=1,050m	6		6.5	V
	Rank V2			6.51		7	
Correlated Colour Temperature		CCT	IF=1,050mA	5,250	5.750		K
CIE Chromaticity Coordinates: X Axis		Х	IF=1,050mA		0.3287		
CIE Chromaticity Coordinates: Y Axis		Υ	IF=1,050mA		0.3417		
Reverse Current		lr	Vr=5V			50	μA
Colour Rendering Index		CRI	IF=1,050mA		72		Ra
Viewing Angle at 50%			2θ1⁄2		120		Deg
Thermal Resistance Junction to	Case		Rθj-c		15		°C / W

Notes: 1. The data is tested by IS tester.

2. Customer's special requirements are also welcome.

Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

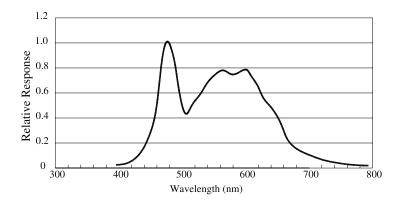
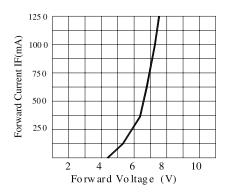
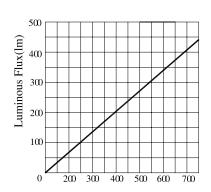


Fig.1 WHITE LED Spectrum VS. WAVELENGTH

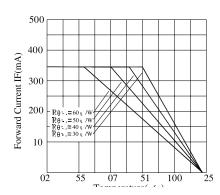


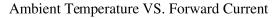


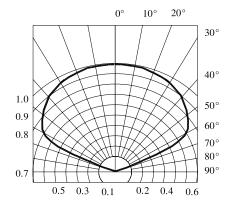


Forward Current VS. Applied Voltage

Forward Current VS. Luminous Flux







Radiation Diagram

Chromaticity Coordinates Specifications for Bin Grading:

Bin	Rank					Bin	Rank				
WB6	Х	0.3327	0.3394	0.3390	0.3324	WB7	Χ	0.3324	0.3390	0.3385	0.3324
	Υ	0.3650	0.3719	0.3591	0.3519		Υ	0.3519	0.3591	0.3465	0.3388
WC6	Х	0.3264	0.3327	0.3324	0.3268	WC7	Χ	0.3268	0.3324	0.3324	0.3272
VVCO	Υ	0.3551	0.3650	0.3519	0.3430		Υ	0.3430	0.3519	0.3388	0.3305
WD6	Х	0.3210	0.3264	0.3268	0.3218	WD7	Х	0.3218	0.3268	0.3272	0.3227
VVD6	Υ	0.3468	0.3551	0.3430	0.3353		Υ	0.3353	0.3430	0.3305	0.3233
WE6	Х	0.3164	0.3210	0.3218	0.3175	WE7	Х	0.3175	0.3218	0.3227	0.3186
	Υ	0.3395	0.3468	0.3353	0.3283		Υ	0.3283	0.3353	0.3233	0.3169

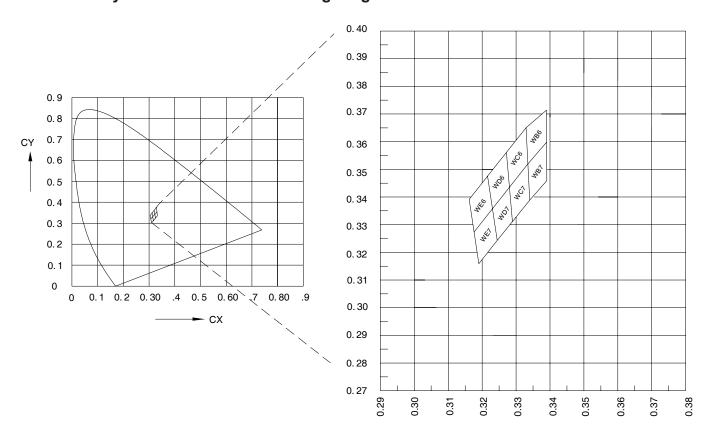
Note: X. Y

Tolerance each Bin limit is ±0.01





Chromaticity Coordinates & Bin Grading Diagram:



Part Number Table

LE	ED Chip	Lens Colour	Part Number
Material	Colour Coordinates		
InGaN/Sapphire	White	Yellow diffused	703-0116

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